



Material Content Data Sheet



Sales Product Name	TLE94108EL			Issued	22. January 2018			
MA#	MA001469236							
Package	PG-SSOP-24-9			Weight*	150.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.240	2.15	2.15	21480	21480
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8917	
wire	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561
	non noble metal	copper	7440-50-8	0.853	0.57	0.57	5657	5657
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1148
encapsulation	plastics	epoxy resin	-	7.965	5.28		52806	
	inorganic material	silicondioxide	60676-86-0	78.440	52.00	57.39	520025	573979
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.244	0.16		1618	
	noble metal	silver	7440-22-4	0.732	0.49	0.65	4854	6472
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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